

PATENT TESSERA 3.0-022

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of: Karavakis et al.

Group Art Unit

Serial No. 08/246,113

Examiner:

Filed:

May 19, 1994

For:

Date: July 19, 1994

METHOD OF ENCAPSULATING DIE AND CHIP CARRIER

RECEIVED

Hon. Commissioner of Patents and Trademarks Washington, D.C. 20231

AUG 0 5 1994 APPLICATION DIVISION

SUBMISSION OF EXECUTED DECLARATION

Sir:

In response to the Notice to File Missing Parts dated June 21, 1994 (a copy of which is enclosed herewith), Applicant herewith encloses the original executed Declaration for the above-identified patent application which was filed on May 19, 1994. Also enclosed is a check in the amount of \$130.00 to cover the surcharge for filing a Declaration on a date later than the filing date of the application.

If there are any additional fees, please charge them to our Deposit Account No. 12-1095.

Respectfully submitted,

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> I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to Commissioner of and Trademarks, Washington, D.C. 20231 July 19, 1994

(Date of Deposit)

Signature:

MARCUS J. MILLET

Typed or Printed Name of Person Signing Certificate